Claims

- 1. An adhesive sheet composed of a mixture of two thermoplastics T1 and T2, wherein
 - a) the adhesive system has a softening temperature of greater than 65°C and less than 125°C,
 - b) a storage modulus G' at 23°C, as measured by test method A, of greater than 10⁷ Pas.
 - c) a loss modulus G" at 23°C, as measured by test method A, of greater than 10⁶ Pas,
- d) and a crossover, as measured by test method A, of less than 125°C.

5

30

- 2. The adhesive sheet of claim 1, characterized in that the layer thickness is between 10 and 100 μm , with particular preference between 30 and 80 μm .
- The adhesive sheet of at least one of the preceding claims, characterized in that thermoplastics T1 and T2 are selected from the groups consisting of copolyamides, polyethyl-vinyl acetates, polyvinyl acetates, polyolefins, polyurethanes, and copolyesters.
- 4. The adhesive sheet of at least one of the preceding claims, characterized in that reactive resins used additionally comprise epoxy resins, and/or phenolic resins and/or novolak resins.
- 5. The use of an adhesive sheet of any one of the above claims for bonding chipmodules in card bodies.
 - 6. The use of an adhesive sheet of any one of the above claims for bonding polyimide-, polyester or epoxy-based chip modules and on PVC, ABS, PET, PC, PP or PE card bodies.
 - 7. A method for producing a heat-activable adhesive tape, characterized in that an adhesive sheet of claims 1 to 4 is coated onto a release paper or a release film.
- 6. The method of claim 7, characterized in that the heat-activable adhesive tape is diecut.

7.	The method of at least one of the preceding claims, characterized in that the heat-
	activable adhesive tape is processed with an implanting die temperature of 150°C.